Canon

FPA-5500iZa

1. ID No	
2. Description	**Scanner**
3. Manufacturer	**Canon**
4. Model	**FPA-5500iZa**
5. Wafer Size	**300mm**
6. Vintage	**2006**
7. Serial Number	
8. Location	

- Configuration & Specification

Description	Specification	Remarks
Reticle		
Size	□6″ t=0.25″	
Surface	2 Layers Cr、3 Layers Cr, HT	
Pellicle	Only pattern surfaces can be installed	
Wafer Size	300mm	
Wafer chuck type	12 Inch Pin chuck	
Exposure System		
Projection Lens	UL61-II	
Magnification	1 : 4	
NA	Auto Variable (0.57~0.45 / 0.01 Resolution)	
Screen Size	26 x 33mm	
Exposure Light	i Line (365nm)	
Optical Component protection	CDA Substitution	
Illumination optical system		
Light source	IZ Light system III	
Manufacturer/Model	4.5Kw Ultra high-pressure mercury lamp	
Light Mode	Ushio Inc. / SUV-4500CIL	
Exposure Control	Choose from normal lighting	
Masking Blade	Cumulative exposure method	
Optical Component protection	Aperture Range: □0.4mm ~ X:26mm, Y:33mm	
Lamp position adjustment	CDA & N2 Substitution	
	3-axis automatic adjustment(X-axis / Y-axis / Z- axis)	

- Configuration & Specification

Description	Specification	Remarks
Main Body		
MMI	Touch panel color LCD (eConsole)	
Body structure	5500 body	
Mount	Hybrid (LM + Air)	
Chamber	Model : CD162 / SN :	
Signal Tower	None	
Logger	None	
Console type	e-console	
Console position	Side (Booth2 L)	
Focus System		
Focus / Leveling		
Detection method	Optical focus method	
Drive method	Wafer Stage drive	
Focus calibration		
Detection Method ALFC	Image processing method by TTR	
Others		
Change in pressure focus	Automatic Correction	
Change in exposure focus	Automatic Correction	
AA System		
Reticle alignment		
Alignment method	Matching with the R-standard mark by FRAS	
Detection Method	Image processing method	
Alignment light	i Line(365nm)Transparent lighting	
Reticle holding method	R/S upper reticle holder adsorption method	

- Configuration & Specification

Description	Specification	Remarks
OFF AXIS Wafer alignment system		
Alignment light	590±60nm (Wavelength switching mode)	
Detection Method	Image processing method	
Measuring mode	AGA method	
Base line detection	Matching with the Stage standard mark	
Mechanical pre-alignment	Circumference non-contact method	
TV pre-alignment	TV Image processing method	
Stage system		
Wafer Stage	FLAT II modification stage 6-axis measurement of laser interferometer	
Exposure range of movement	XY : ±165mm	
Compatible with laser wavelength variation	Wavelength change correction function using barometer (standard)	
Laser wavelength correction	Real -time correction by wavelength tracker	
Wafer transport system		
Wafer Transport		
Inline	Left to right (Standard) Front side / Open Cassette	
Chuck maintenance unit	Equipment front-side access	
Auto feeder type	FR type – Relay unit (Reject carrier 5 Slot)	

- Configuration & Specification

Description	Specification	Remarks
Reticle system		
Reticle Changer		
Number of Reticle storage	14ea (Standard) Nikon type	
Expansion library		
Number of Reticle storage	15ea (Total 29ea)	
Pellicle foreign object inspection device	Yes	
Reticle barcode reader	2D	
Cassette barcode reader	Yes (3 of 9 barcode)	
Others		
Failure parts	None	
Missing Parts	None	
	HDD is not included	
Construction	Main Body, Relay Unit	